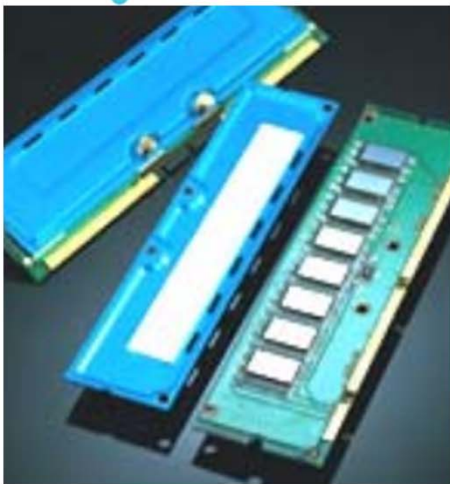


STFLEX



Thermal Interface Material

445-743) 경기도 화성시 봉담읍 와우리 수원대학교 창업보육센터 1001호

TEL : 070-8742-3551

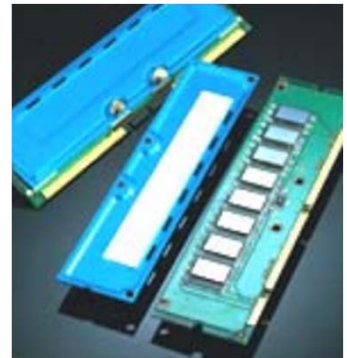
FAX : 031-898-8522

<http://www.stflex.co.kr>

TIM (Thermal Interface Material)

Typical Applications

- Computer and peripherals
- Heat Pipe assemblies
- CDROM / DVD cooling
- Telecommunications
- Memory modules
- Between CPU and heatsink



Key

Benefits

- High thermal performance, cost-effective solution
- Electrically isolating
- Fiberglass reinforced for puncture, shear and tear Resistance
- Highly conformable, low hardness

구분	Composition	TMT-Pad M150	TMT-Pad180	TMT-Pad300	TMT-PCM45C	Test Method
물리적특성	색상	Dark Gray	Dark Gray	Dark Gray	Gray	Visual
	두께 (mm)	0.1 ~ 20.0	0.1 ~ 20.0	0.1 ~ 20.0	0.25	ASTM D374
	비중	2.3	2.3	2.6	2.0	ASTM D792
	강도 (Shore)	25	40	60	>60	ASTM D2240
전기적특성	절연파괴전압 (VAC)	>6000	>6000	>6000	>6000	ASTM D149
	유전상수 (1000Hz)	6	6	6.5	>6.5	ASTM D150
	체적저항률 (Ω.cm)	>10 ¹⁷	>10 ¹⁷	>10 ¹⁶	5.2*10 ¹⁶	ASTM D149
열적특성	열전도율 (W/m.k)	1.5	1.8	3.0	3.0	
	사용온도 (°C)	-40 ~ 200	-40 ~ 200	-40 ~ 200	45°C (Phase Change)	